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A									A
в	PCB LOGO								в
	LOGO ESD Logo								
	PCB LOGO Texas Instruments								
	ZZ1								
с	Label Assembly Note This Assembly Note is for PCB labels only ZZ2								с
	ZZ2 <u>Assembly Note</u> These assemblies are ESD sensitive, ESD precautions shall be observed. ZZ3								
	ZZ3 Assembly Note These assemblies must be clean and free from flux and all contaminants. Use of TZZ4								
	Assembly Note These assemblies must comply with workmanship standards IPC-A-610 Class 2,	unless otherwise specified.							
D									D
							Designed for: Public Release Mod. Date: 10 Project Title: Single Chip 2-Wire Loop Powered, 4 to 2 Sheet Title: Sheet Title: Assembly Variant: 001 Sheet	0/21/2014 20MA Curre	Transmitte
		Texas Instruments and/or its licensors do not warrant the accuracy or warrant that this design will meet the specifications, will be suitable for licensors do not warrant that the design is production worthy. You sho	r completeness of this specification or a r your application or fit for any particula	ny information contained therein. Texas Inst r purpose, or will operate in an implementation lesion implementation to confirm the system	truments and/or its licensors do n on. Texas Instruments and/or its functionality for your application	Number: TIDA-00247 Rev: E1 SVN Rev: Not in version control Drawn By: Engineer: SHARAD YADAV	Sheet Title: Assembly Variant: 001 Sheet File: Hardware ANSI-B.SchDoc S Contact: http://www.ti.com/support S	Size: B http://www.ti.com	
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